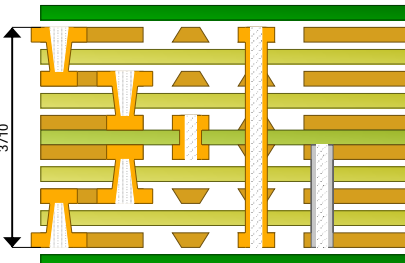



Layer	Stack up	Description	Base Thickness	Processed Thickness	εr	Impedance ID	Copper Coverage	Comments
1		Liquid Photolmageable Mask	25,00	4,00				
		Copper Foil	18,00	35,00			50,00	
		PrePreg 1080	75,00	75,00	4,20			
2		Copper Foil	18,00	35,00			50,00	
		PrePreg 1080	75,00	75,00	4,20			
3			18,00	35,00			80,00	
		FR4 Core	3200,00	3200,00	4,20			
4			18,00	35,00			50,00	
		PrePreg 1080	75,00	75,00	4,20			
5		Copper Foil	18,00	35,00			50,00	
		PrePreg 1080	75,00	75,00	4,20			
6		Copper Foil	18,00	35,00			50,00	
		Liquid Photolmageable Mask	25,00	4,00				

Copper Thickness = 210,000 | Dielectric Thickness = 3500,000 | Solder Mask Thickness = 50,000 | Stack Up Thickness = 3710,000 | Stack Up Thickness with Soldermask = 3760,000 | Stack Up Cost = 34,00 |

Notes

StackName: WISI 6 Layer EM-888	Version:	Revision:	Modification:	Date of Revision:	Editor	Page 1/1	
Date: 2018-04-25	Associated Documents:						
Author: Kenneth Jonsson							
Department: Technical							
Site: Sweden							